

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ISC012N04NM6	**Issued**	08. April 2022
MA#	MA005710962		
Package	PG-TDSON-8-36	**Weight***	115.79 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.182	1.02	1.02	10206	10206
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.049	0.04		422	
	non noble metal	copper	7440-50-8	48.769	42.13	42.18	421204	421753
wire	noble metal	gold	7440-57-5	0.043	0.04	0.04	375	375
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		716	
	plastics	epoxy resin	-	6.546	5.65		56533	
	inorganic material	silicondioxide	60676-86-0	34.800	30.06	35.78	300557	357806
leadfinish	non noble metal	tin	7440-31-5	1.392	1.20	1.20	12018	12018
plating	noble metal	silver	7440-22-4	0.194	0.17	0.17	1674	1674
solder	non noble metal	tin	7440-31-5	0.031	0.03		263	
	noble metal	silver	7440-22-4	0.038	0.03		329	
	non noble metal	lead	7439-92-1	1.457	1.26	1.32	12581	13173
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005			44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	non noble metal	copper	7440-50-8	17.131	14.80	14.81	147959	148151
clip plating	noble metal	silver	7440-22-4	1.059	0.91	0.91	9147	9147
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			8	
	non noble metal	iron	7439-89-6	0.003			26	
	non noble metal	copper	7440-50-8	2.971	2.57	2.57	25663	25697
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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